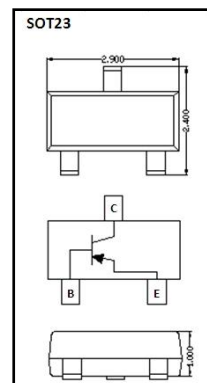


DATA SHEET

SS8550

- ◇ Capable of 300mWatts of Power Dissipation
- ◇ Operating and Storage Junction Temperatures: -55°C to 150°C
- ◇ Surface Mount SOT-23 Package
- ◇ RoHS compliant / Green EMC
- ◇ Collector current: $I_C=1.5\text{A}$

Device Marking Code	
SS8550	Y2



MAXIMUM RATINGS ($T_a=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{CB0}	Collector-Base Voltage	-40	V
V_{CE0}	Collector-Emitter Voltage	-25	V
V_{EB0}	Emitter-Base Voltage	-5	V
I_C	Collector Current	-1.5	A
P_C	Collector Power Dissipation	300	mW
$R_{\theta JA}$	Thermal Resistance From Junction To Ambient	417	$^{\circ}\text{C}/\text{W}$
T_j	Junction Temperature	150	$^{\circ}\text{C}$
T_{stg}	Storage Temperature	$-55\sim+150$	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS @ 25°C Unless Otherwise Specified

Symbol	Parameter	Test Conditions	Min	Max	Units
V_{CE0}	Collector-emitter breakdown voltage	$I_C=-0.1\text{mA}$, $I_B=0$	-25		V
V_{CB0}	Collector-base breakdown voltage	$I_C=-100\mu\text{A}$, $I_E=0$	-40		V
V_{EB0}	Emitter-base breakdown voltage	$I_E=-100\mu\text{A}$, $I_C=0$	-5.0		V
I_{CB0}	Collector cutoff current	$V_{CB}=-40\text{V}$, $I_E=0\text{V}$		-100	nA
I_{EB0}	Emitter cut-off current	$V_{EB}=-5\text{V}$, $I_C=0$		-100	nA
I_{CE0}	Collector cut-off current	$V_{CB}=-20\text{V}$, $I_E=0$		-100	nA

h_{FE}	DC current gain	$h_{FE(1)} I_C=-100mA, V_{CE}=-1V$ $h_{FE(2)} I_C=-800mA, V_{CE}=-1V$	120 40	400	
$V_{CE(sat)}$	Collector-emitter saturation voltage	$I_C=-800mA, I_B=-80mA$		-0.5	V
$V_{BE(sat)}$	Base-emitter saturation voltage	$I_C=-800mA, I_B=-80mA$		-1.2	V
V_{BE}	Base-emitter voltage	$V_{CE}=-1V, I_C=-10mA$		-1	V
f_T	Transition frequency	$I_C=-20mA, V_{CE}=-6V, f=30MHz$	150		MHZ
C_{ob}	Collector output capacitance	$V_{CB}=-10V, I_E=0V, f=1MHz$		20	pF

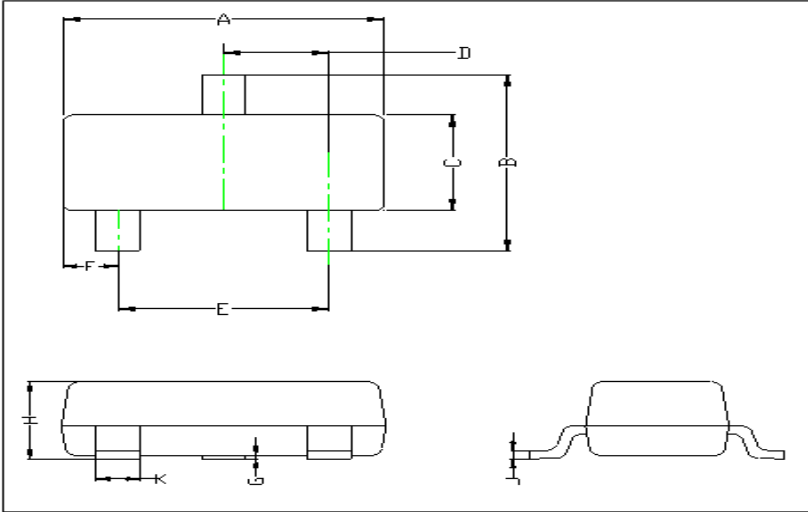
CLASSIFICATION OF $h_{FE(1)}$

Rank	L	H
Range	120-200	200-350

ORDERING INFORMATION

Device	Package	Shipping	Tape wide	Emboss pitch	Tape specification	Notes
SS8550	SOT23	Tape & Reel 3000pcs / 7" Reel	8mm	4mm	Conductive	

PACKAGE DIMENSIONS

Package Outline : SOT23		
		
SOT23 Package Outline		
Symbol	Dimensions in mm	
	Min.	Max.
A	2.800	3.040
B	2.100	2.640
C	1.200	1.400
D	0.890	1.030
E	1.780	2.050
F	0.450	0.600
G	0.013	0.100
H	0.900	1.110
J	0.090	0.180
K	0.370	0.510

Note:
1. Halogen free ,EMC
2. Pb free solder
3. Lead thickness solder plating
4. Lead frame CAC-5
5. Other Tolerance ± 0.05
6. Dimensions are exclusive of Burrs Mold Flash and Tie Bar extrusions
7. Unit : mm

NOTICE

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